TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSVI)

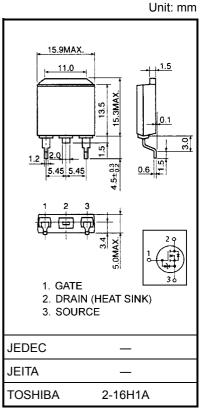
2SK3125

DC-DC Converter, Relay Drive and Motor Drive Applications

- Low drain-source ON resistance: $RDS(ON) = 5.3 \text{ m}\Omega \text{ (typ.)}$
- High forward transfer admittance: $|Y_{fs}| = 60 \mathrm{S}$ (typ.)
- Low leakage current: $I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 30 \text{ V)}$
- Enhancement-model: $V_{th} = 1.5 \sim 3.0 \text{ V (V}_{DS} = 10 \text{ V}, I_D = 1 \text{ mA)}$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage	;	V _{DSS}	30	V	
Drain-gate voltage (F	$R_{GS} = 20 \text{ k}\Omega$	V_{DGR}	30	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	I _D	70	Α	
	Pulse (Note 1)	I _{DP}	210		
Drain power dissipat	ion (Tc = 25°C)	PD	150	W	
Single pulse avalance	he energy (Note 2)	E _{AS}	955	mJ	
Avalanche current		I _{AR}	70	Α	
Repetitive avalanche	e energy (Note 3)	E _{AR}	15	mJ	
Channel temperature	9	T _{ch}	150	°C	
Storage temperature	range	T _{stg}	-55~150	°C	



Weight: 3.65 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit	
Thermal resistance, channel to case	R _{th (ch-c)}	0.833	°C/W	

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 25 V, T_{ch} = 25°C, L = 140 μH , R_G = 25 Ω , I_{AR} = 70 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.

Electrical Characteristics (Ta = 25°C)

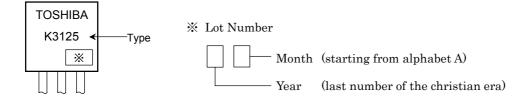
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Chara	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage curr	ent	I _{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cut-OFF cui	rent	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	_	_	100	μА
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10$ mA, $V_{GS} = 0$ V	30	_	_	V
Gate threshold voltage		V _{th}	V _{DS} = 10 V, I _D = 1 mA	1.5	_	3.0	V
Drain-source ON	resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 30 A	_	5.3	7.0	mΩ
Forward transfer a	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 30 A	30	60	_	S
Input capacitance		C _{iss}			4600	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	1400	_	pF
Output capacitance		Coss		_	2300	_	
Switching time	Rise time	t _r	$V_{GS} = 30 \text{ A}$ $V_{GS} = 0.5 \Omega$ $V_{DD} \approx 15 \text{ V}$ $V_{DD} \approx 15 \text{ V}$ $V_{DD} \approx 15 \text{ V}$	_	25	_	- ns
	Turn-ON time	t _{on}		_	40	_	
	Fall time	t _f		_	150		
	Turn-OFF time	t _{off}		_	425	_	
Total gate charge (gate-source plus gate-drain)		Qg			130		nC
Gate-source charge		Q _{gs}	$V_{DD} \simeq 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 70 \text{ A}$	_	90	_	
Gate-drain ("miller") charge		Q _{gd}		_	40	_	

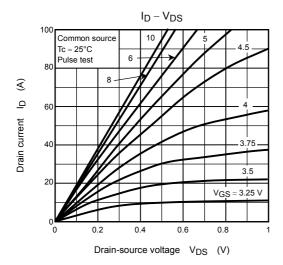
Source-Drain Ratings and Characteristics (Ta = 25°C)

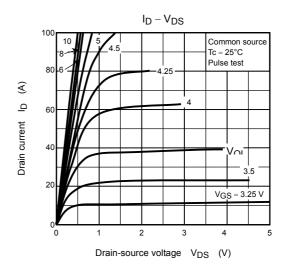
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_		_	70	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	210	Α
Forward voltage (diode)	V_{DSF}	$I_{DR} = 70 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 70 \text{ A}, V_{GS} = 0 \text{ V},$		150	_	ns
Reverse recovery charge	Q _{rr}	$dI_{DR}/dt = 50 A/\mu s$		225		nC

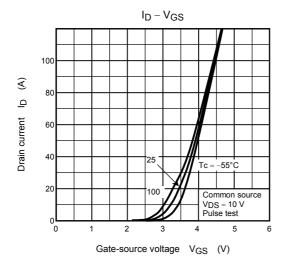
Marking

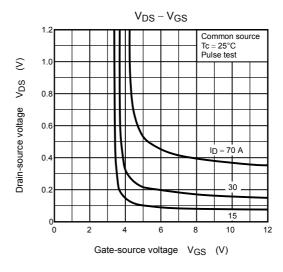


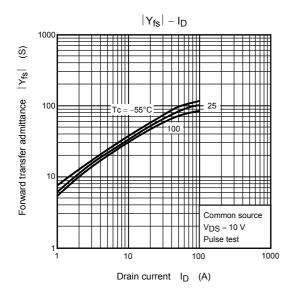
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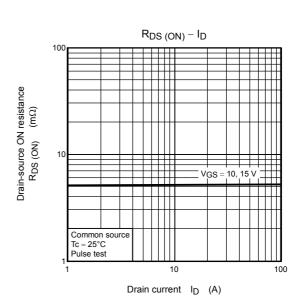




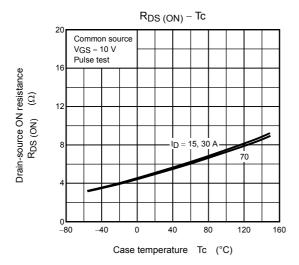


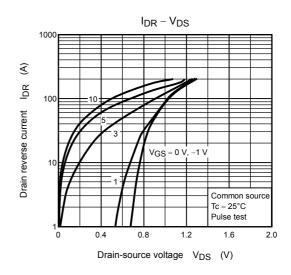


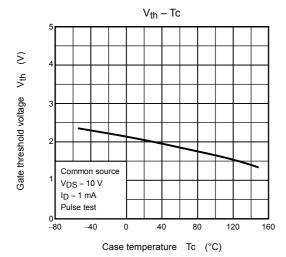


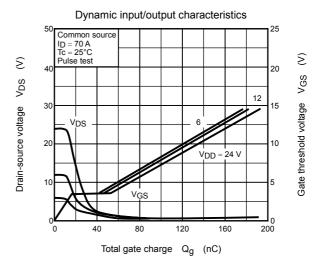


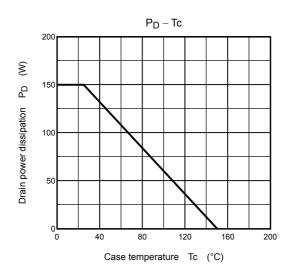
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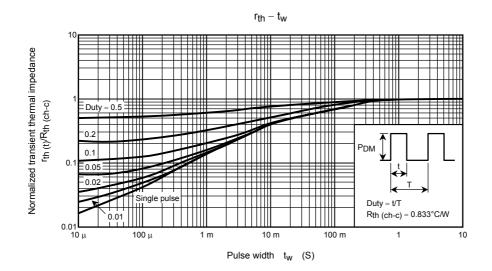


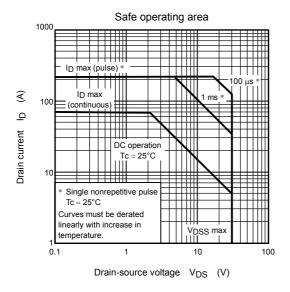


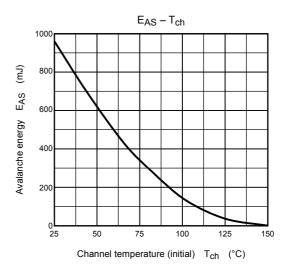


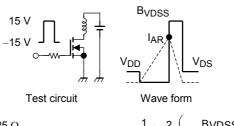












$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 25~V,~~L = 140~\mu H \end{aligned} \qquad EAS &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right) \end{aligned}$$

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